

M1

Interstage Interface Panel  
FD1 Board N.2 Rev 1.0

M2

SpaceLab UFSC 2020

FD2



TP1



JTAG/UART N3

2

1

14

13

+Z  
-X

TP2



JTAG/UART N4

2

1

14

13

+RBF  
-RBF

M3

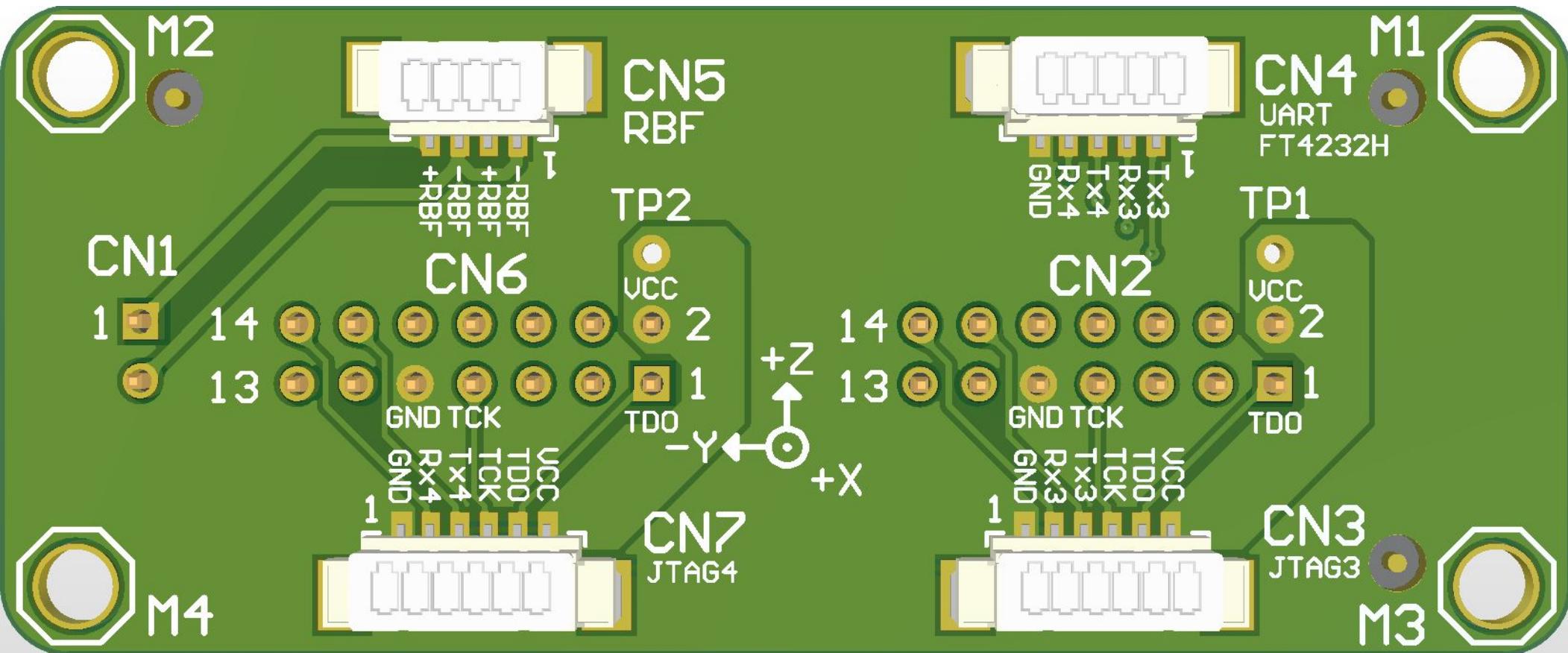
FD3 line limit  
external  
connectors



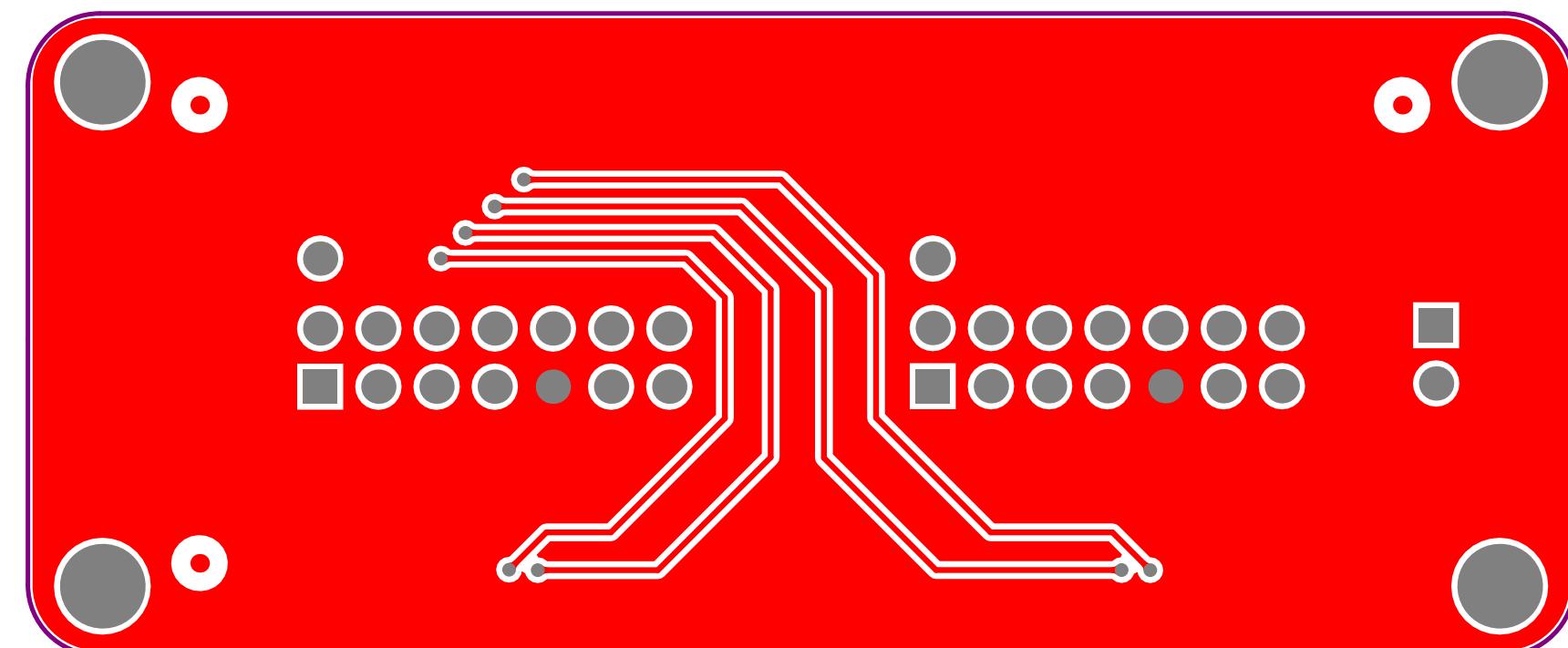
structure contact  
area

M4



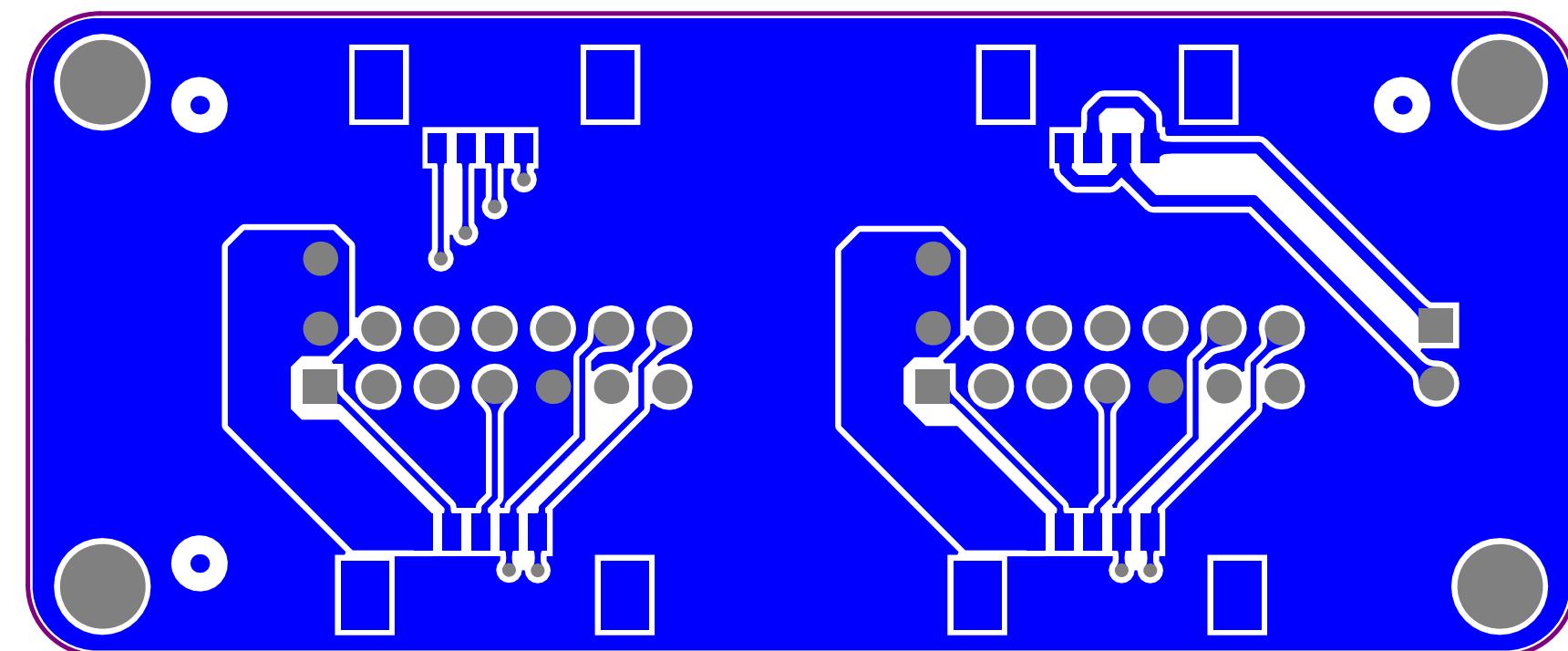


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



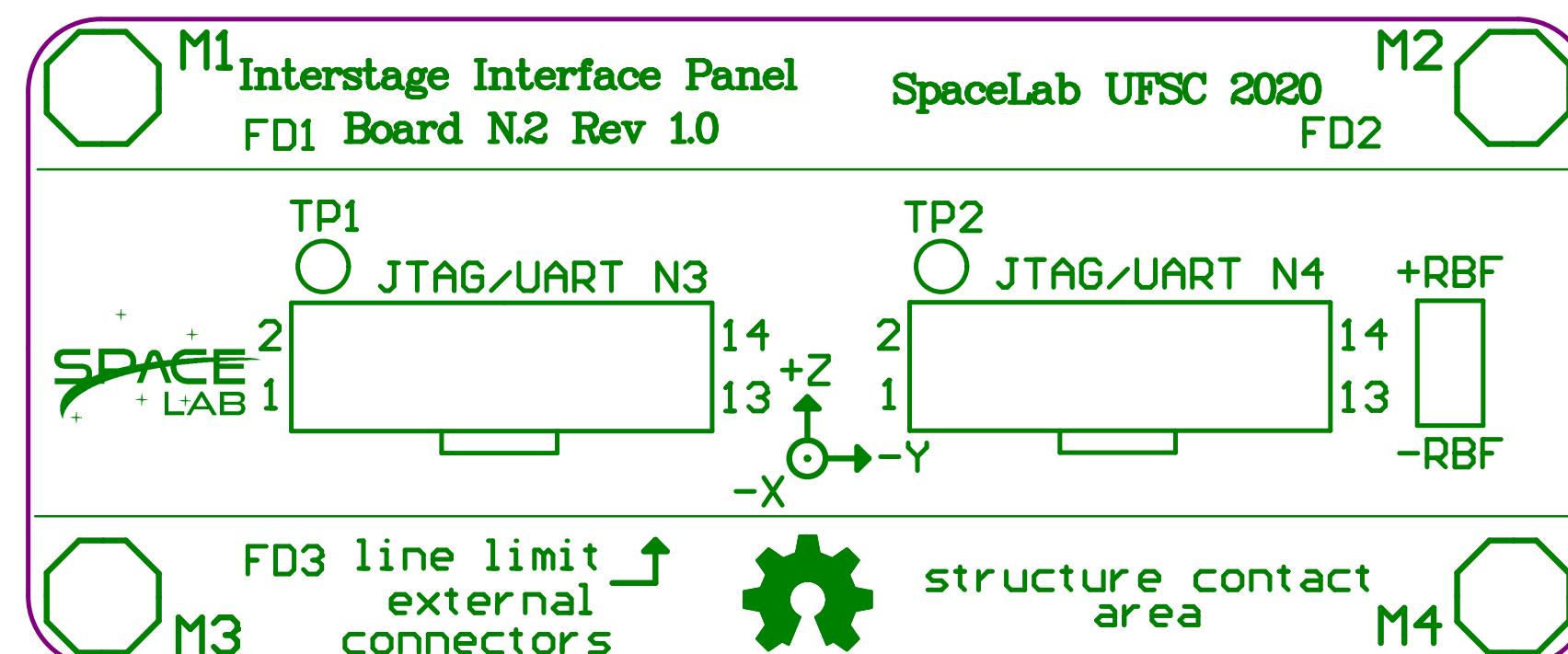
<b>TITLE:</b> IIP N.2 BOARD RBF		<b>REV:</b> 1.0	<b>DATE:</b> 02/07/2020
<b>MATERIAL:</b> FR4		<b>Silkscreen color:</b> white	<b>Project:</b> IIP
<b>Board Thickness:</b> 1.6mm	<b>Layers:</b> 02		Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
<b>PCB Surface:</b> HASL	<b>Drawing:</b> Yan C. de Azeredo		

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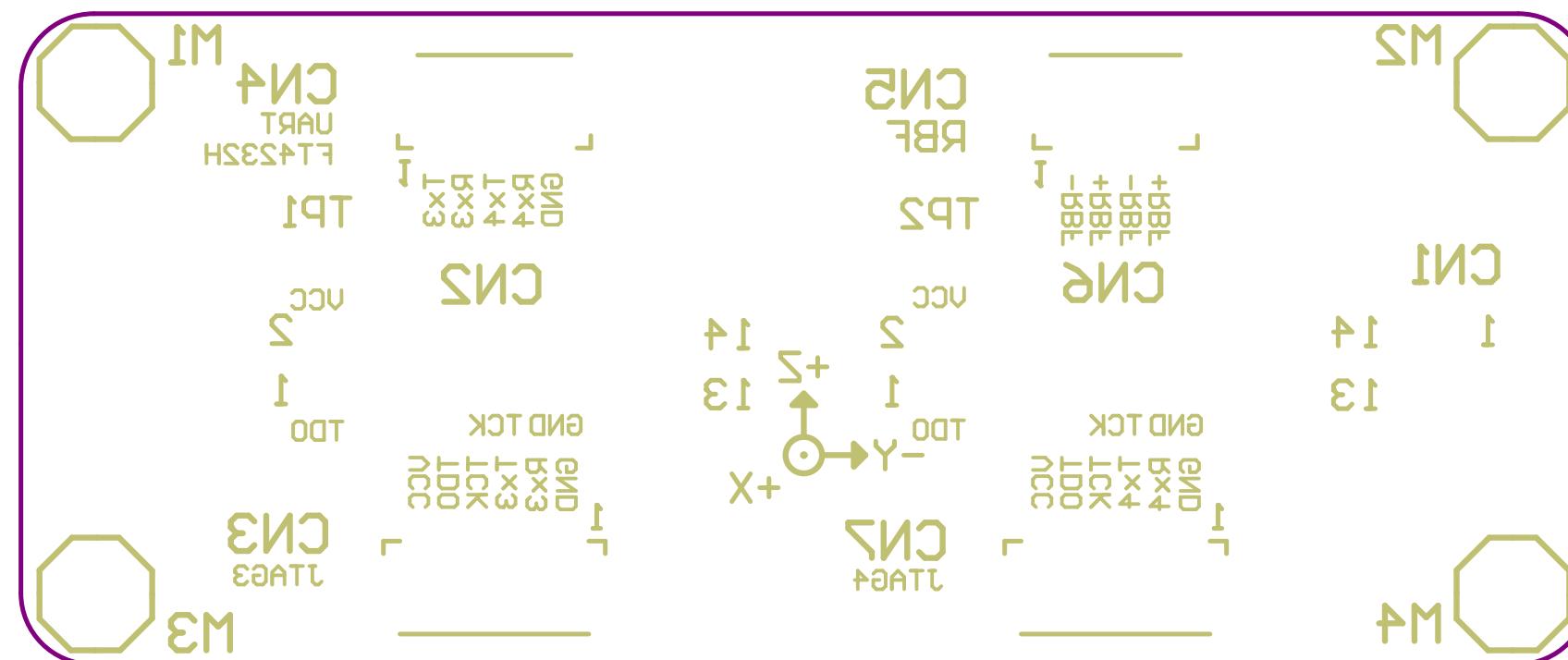
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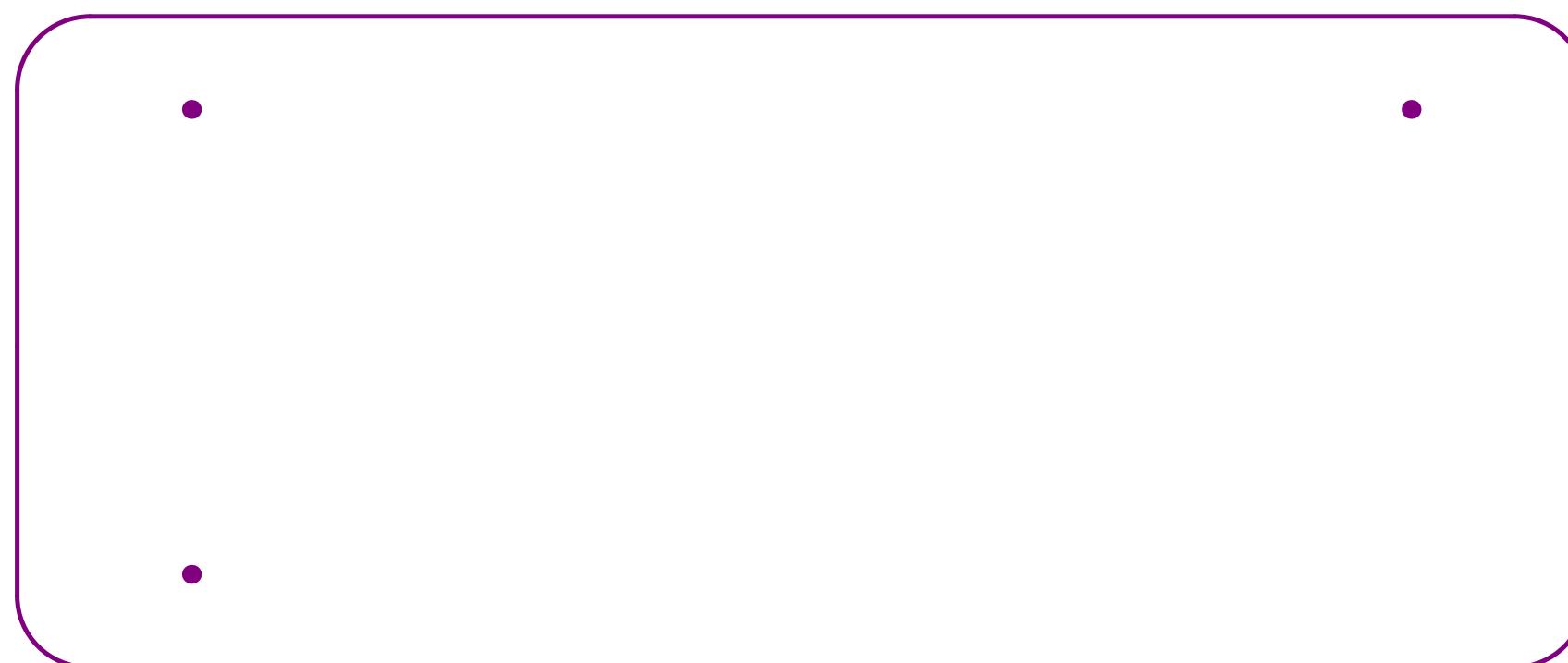
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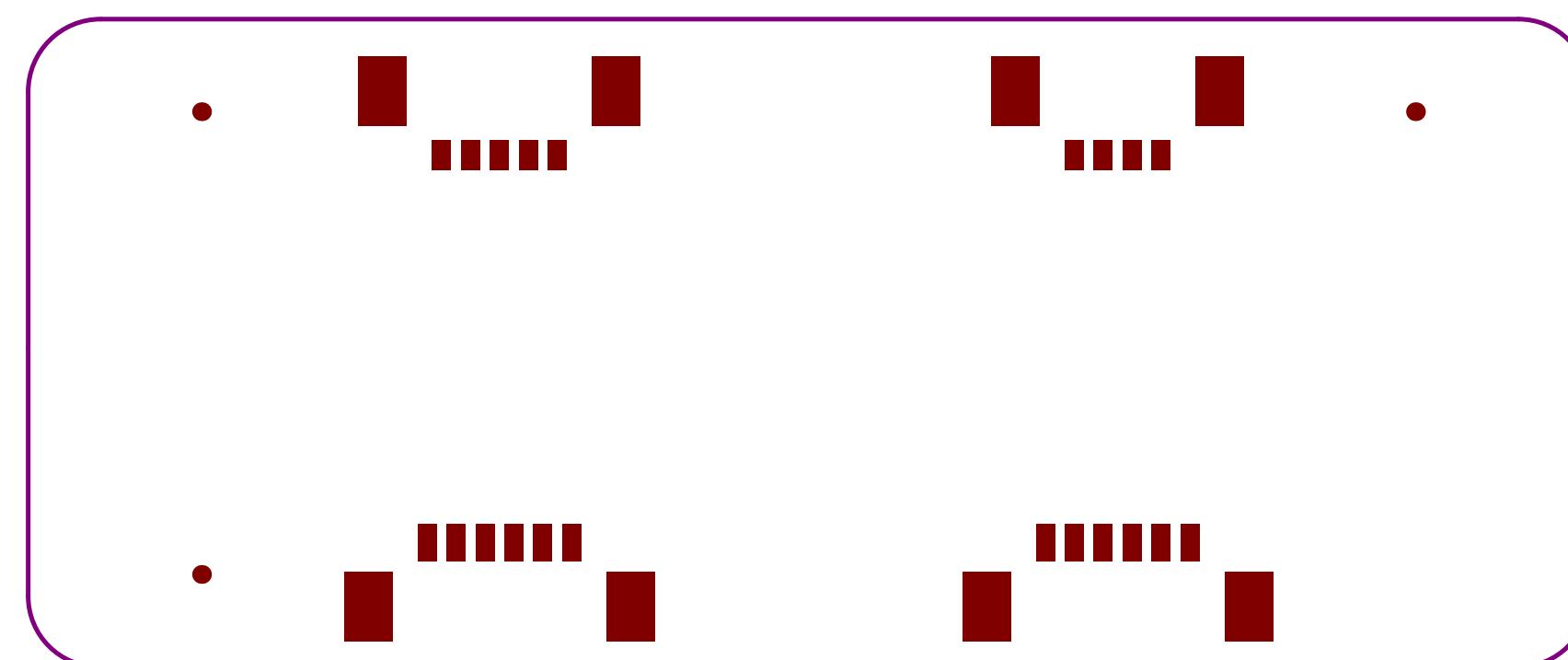
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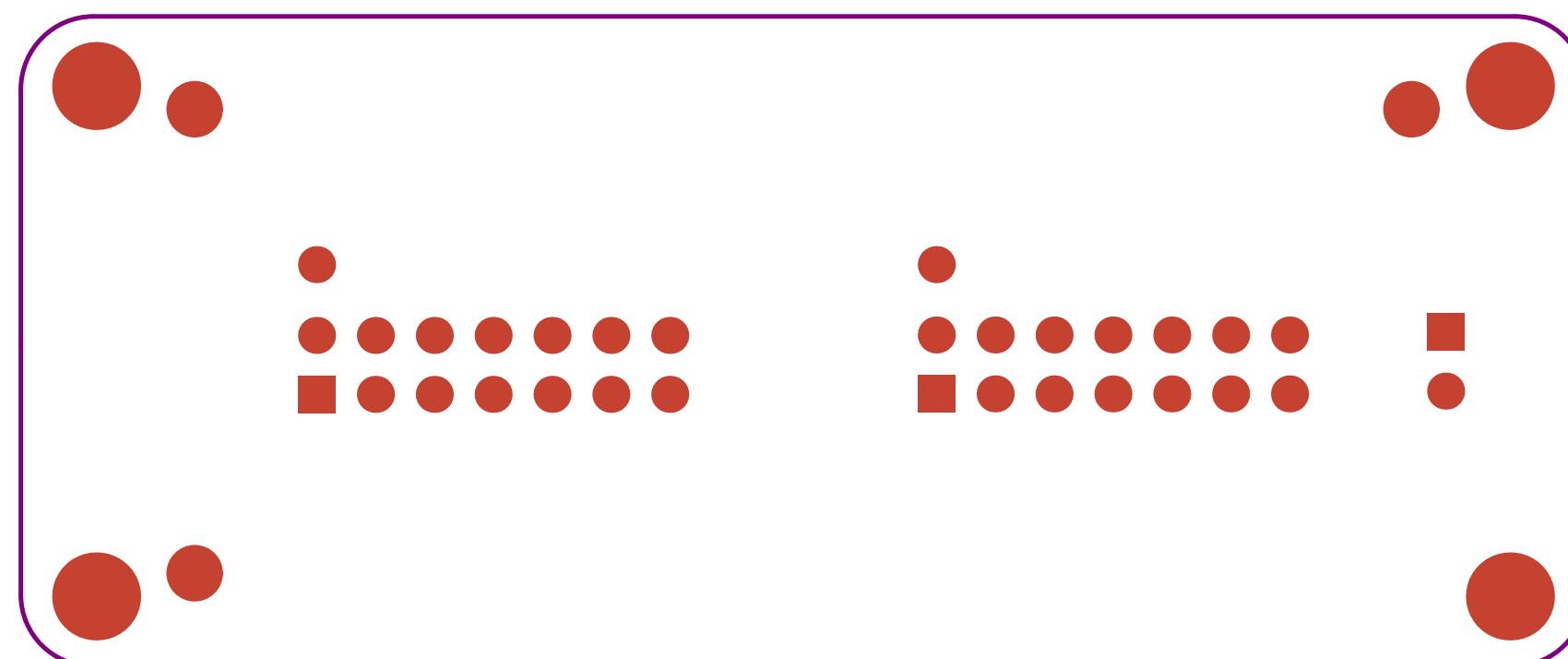
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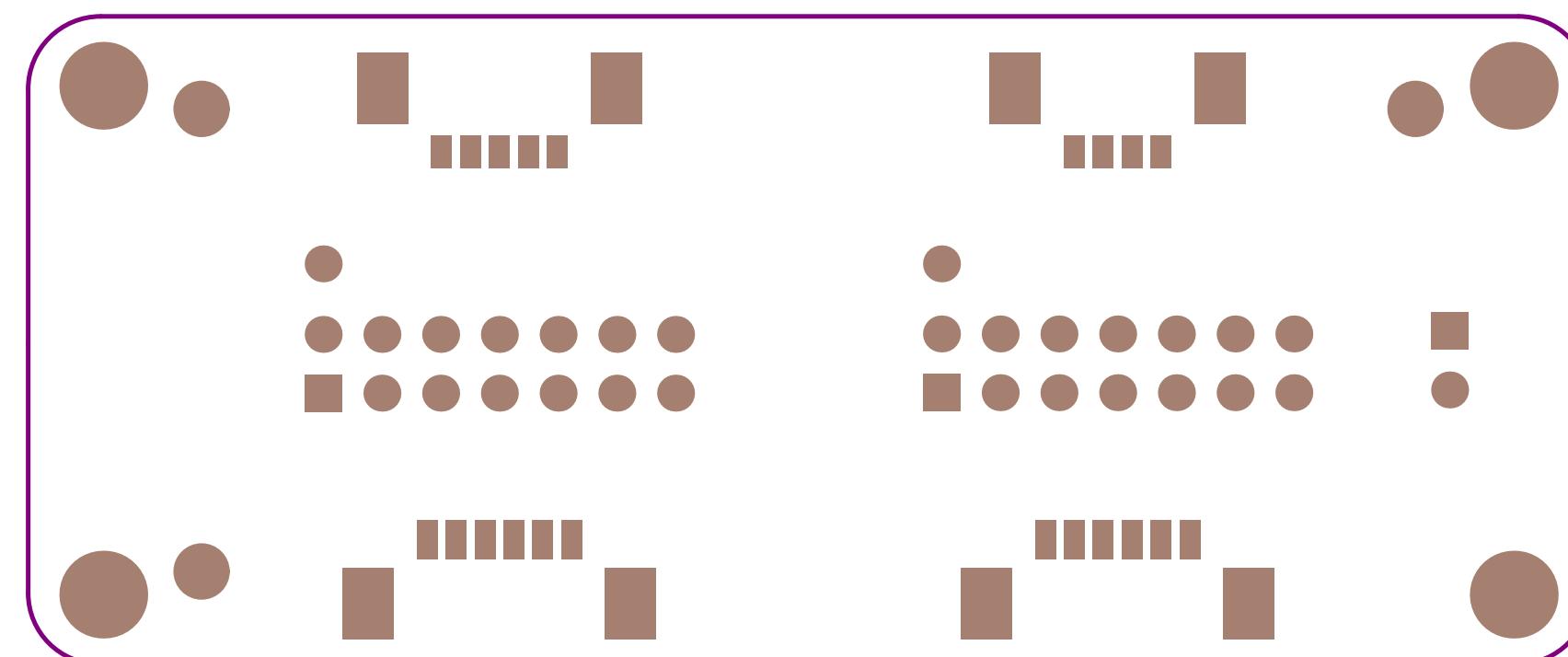
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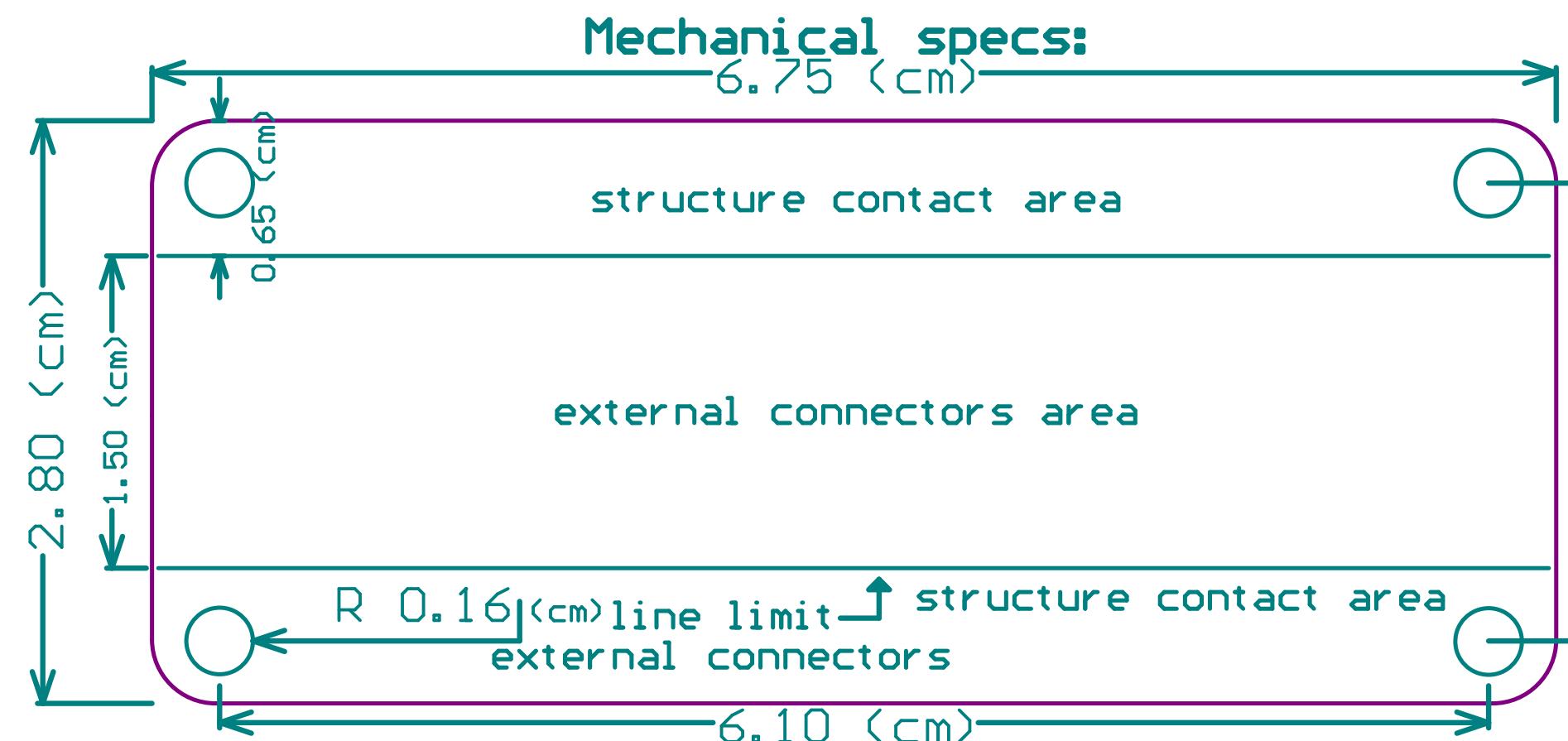
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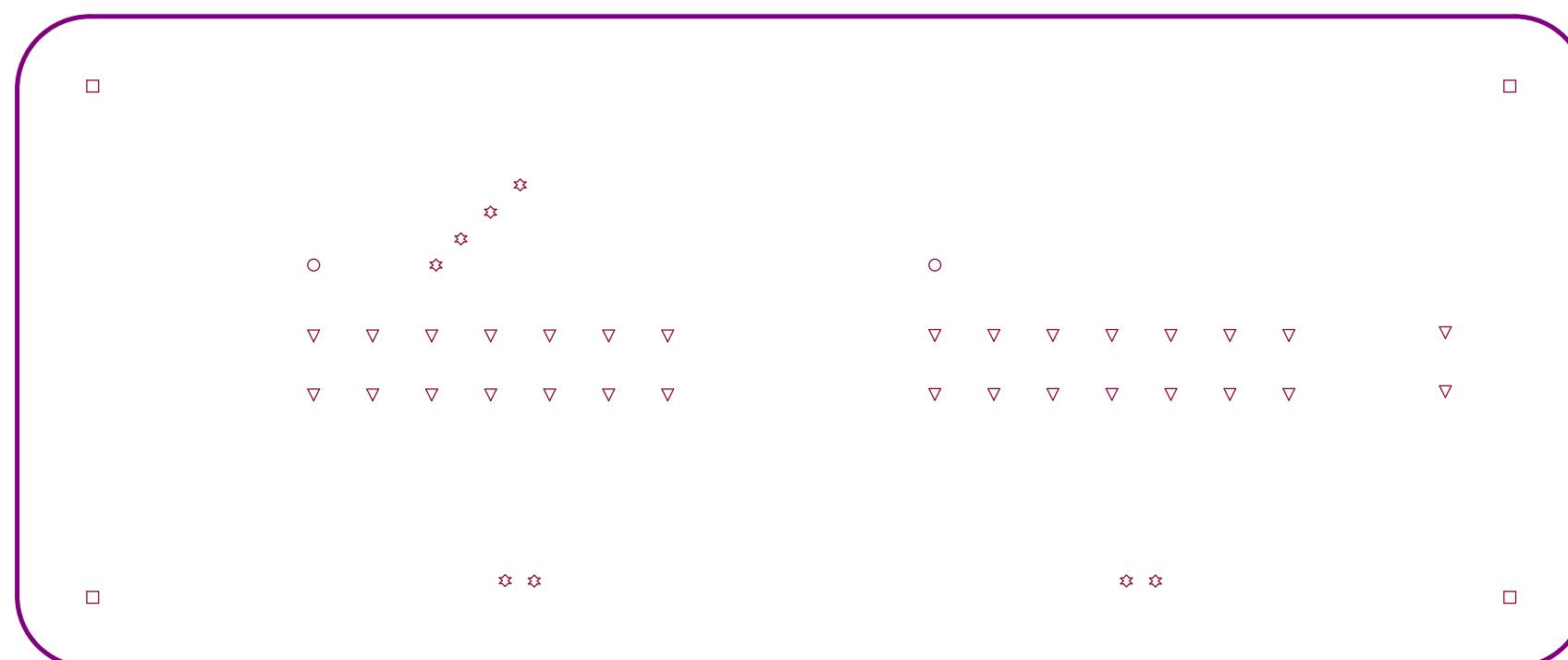
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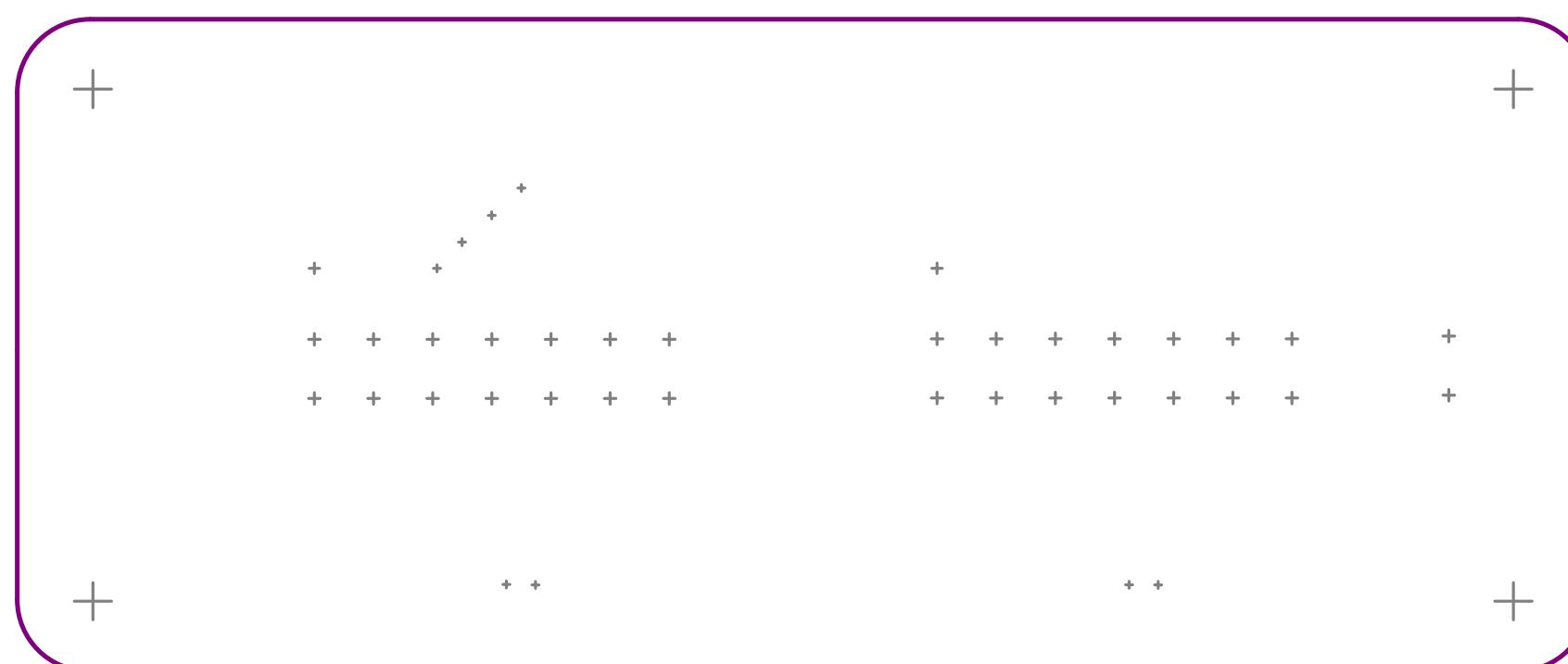
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
◊	8	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30m0mx0
○	2	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c150h90
▽	30	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
□	4	3.200mm (125.98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c370h320
<b>44 Total</b>								

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